

HM79S-63470LF summary material content, BI Technologies Corporation

Index	Item	Material Name	Element Composition	CAS No	Material Mass (g)	Composition (g)
1	CORE	Ferrite Core	Iron Oxide	1317-61-9	0.3150	0.2048
			Copper Oxide	1317-38-0		0.0347
			Nickel Oxide	13113-99-1		0.0284
			Zinc Oxide	1314-13-2		0.0473
2	COIL	Polyurethane Enamelled Copper Wire	Copper	7440-50-8	0.0400	0.0392
			Polyurethane Resin	-		0.0008
3	SOLDER	Lead Free Solder	Sn 96.5	7440-31-5	0.0090	0.0087
			Ag 3.0	7440-21-3		0.0003
			Cu 0.5	7440-50-8		0.0000
4	ADHESIVE	Epoxy Resin	Modified Epoxy Resin	250-38-6	0.0100	0.0055
			Hardener	007631-86-9		0.0010
			Aluminium Hydroxide	21645-51-2		0.0025
			Decabromo Diphenyethane	84852-53-9		0.0010

Total Weight	0.3740
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HM79S-74330LF summary material content, BI Technologies Corporation

Index	Item	Material Name	Element Composition	CAS No	Material Mass (g)	Composition (g)
1	CORE	Ferrite Core	Iron Oxide	1317-61-9	0.6960	0.4524
			Copper Oxide	1317-38-0		0.0766
			Nickel Oxide	13113-99-1		0.0626
			Zinc Oxide	1314-13-2		0.1044
2	COIL	Polyurethane Enamelled Copper Wire	Copper	7440-50-8	0.1180	0.1156
			Polyurethane Resin	-		0.0024
3	SOLDER	Lead Free Solder	Sn 96.5	7440-31-5	0.0280	0.0270
			Ag 3.0	7440-21-3		0.0008
			Cu 0.5	7440-50-8		0.0001
4	ADHESIVE	Epoxy Resin	Modified Epoxy Resin	250-38-6	0.0310	0.0171
			Hardener	007631-86-9		0.0031
			Aluminium Hydroxide	21645-51-2		0.0078
			Decabromo Diphenyethane	84852-53-9		0.0031

Total Weight	0.8730
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HM79S-105271LF summary material content, BI Technologies Corporation

Index	Item	Material Name	Element Composition	CAS No	Material Mass (g)	Composition (g)
1	CORE	Ferrite Core	Iron Oxide	1317-61-9	1.3330	0.8665
			Copper Oxide	1317-38-0		0.1466
			Nickel Oxide	13113-99-1		0.1200
			Zinc Oxide	1314-13-2		0.2000
2	COIL	Polyurethane Enamelled Copper Wire	Copper	7440-50-8	0.2350	0.2303
			Polyurethane Resin	-		0.0047
3	SOLDER	Lead Free Solder	Sn 96.5	7440-31-5	0.0430	0.0415
			Ag 3.0	7440-21-3		0.0013
			Cu 0.5	7440-50-8		0.0002
4	ADHESIVE	Epoxy Resin	Modified Epoxy Resin	250-38-6	0.0320	0.0176
			Hardener	007631-86-9		0.0032
			Aluminium Hydroxide	21645-51-2		0.0080
			Decabromo Diphenyethane	84852-53-9		0.0032

Total Weight	1.6430
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HM79S-125681LF summary material content, BI Technologies Corporation

Index	Item	Material Name	Element Composition	CAS No	Material Mass (g)	Composition (g)
1	CORE	Ferrite Core	Iron Oxide	1317-61-9	2.1580	1.4027
			Copper Oxide	1317-38-0		0.2374
			Nickel Oxide	13113-99-1		0.1942
			Zinc Oxide	1314-13-2		0.3237
2	COIL	Polyurethane Enamelled Copper Wire	Copper	7440-50-8	0.4520	0.4430
			Polyurethane Resin	-		0.0090
3	SOLDER	Lead Free Solder	Sn 96.5	7440-31-5	0.0360	0.0347
			Ag 3.0	7440-21-3		0.0011
			Cu 0.5	7440-50-8		0.0002
4	ADHESIVE	Epoxy Resin	Modified Epoxy Resin	250-38-6	0.0410	0.0226
			Hardener	007631-86-9		0.0041
			Aluminium Hydroxide	21645-51-2		0.0103
			Decabromo Diphenyethane	84852-53-9		0.0041

Total Weight	2.6870
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